

LNPT[™] STAT-KON[™] COMPOUND MFD03

MF-15

REGION EUROPE

DESCRIPTION

LNP STAT-KON MFD03 compound is based on Polypropylene (PP) resin containing conductive carbon powder and 15% glass fiber. Added features of this grade include: Electrically Conductive.

GENERAL INFORMATION

Features	Electrically Conductive, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber, Carbon Powder
Polymer Types	Polypropylene, Unspecified (PP, Unspecified)
Processing Techniques	Injection Molding

INDUSTRY

Electrical and Electronics
Industrial

SUB INDUSTRY

Electronic Components
Material Handling

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yield, 5 mm/min	60	MPa	ISO 527
Tensile Stress, break, 5 mm/min	59	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	2.4	%	ISO 527
Tensile Strain, break, 5 mm/min	2.4	%	ISO 527
Tensile Modulus, 1 mm/min	4300	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	88	MPa	ISO 178
Flexural Stress, break, 2 mm/min	50	MPa	ISO 178
Flexural Strain, break, 2 mm/min	3.7	%	ISO 178
Flexural Modulus, 2 mm/min	4100	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched 80*10*4 +23°C	20	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
CTE, 23°C to 60°C, flow	5.E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	1.34E-04	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	154	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	127	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Mold Shrinkage, flow ⁽²⁾	0.5 – 1	%	SABIC method
Density	1.07	g/cm ³	ISO 1183
Water Absorption, (23°C/24hrs)	0.02	%	ISO 62-1

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CHEMISTRY THAT MATTERS[™]

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
ELECTRICAL ⁽¹⁾			
Surface Resistivity ⁽³⁾	1.E+03 – 1.E+06	Ω	ASTM D257
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	225 – 250	°C	
Front - Zone 3 Temperature	240 – 250	°C	
Middle - Zone 2 Temperature	215 – 225	°C	
Rear - Zone 1 Temperature	195 – 205	°C	
Mold Temperature	30 – 50	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Measurement meets requirements as specified in ASTM D4496.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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